

64. A semiconductor substrate processing apparatus, comprising:  
a carry-in section for carrying in a semiconductor substrate having a surface on which a circuit is formed;  
a plated metal film forming unit for forming a plated metal film on said semiconductor substrate which has been carried in;  
an annealing unit for annealing said semiconductor substrate;  
a cleaning unit for cleaning said semiconductor substrate;  
a film thickness measuring unit for measuring and/or detecting a film thickness of said film and/or a surface state of said film formed on said semiconductor substrate; and  
a transport mechanism for transporting said semiconductor substrate between said units.

65. A semiconductor substrate processing apparatus, comprising:  
a carry-in section for carrying in a semiconductor substrate having a surface on which a circuit is formed;  
a plated metal film forming unit for forming a plated metal film on said semiconductor substrate which has been carried in;  
an annealing unit for annealing said semiconductor substrate;  
a cleaning unit for cleaning said semiconductor substrate;  
a reinforcing seed layer forming unit for forming a reinforcing seed layer on said semiconductor substrate; and  
a transport mechanism for transporting said semiconductor substrate between said units.

66. A semiconductor substrate processing apparatus, comprising:  
a carry-in section for carrying in semiconductor substrate having a surface on which a circuit is formed;  
a plated metal film forming unit for forming a plated metal film on said semiconductor substrate which has been carried in;  
an annealing unit for annealing said semiconductor substrate;

a cleaning unit for cleaning said semiconductor substrate;  
a seed layer forming unit for forming a seed layer on said semiconductor substrate; and  
a transport mechanism for transporting said semiconductor substrate between said units.

67. A semiconductor substrate processing apparatus, comprising:  
a carry-in section for carrying in a semiconductor substrate having a surface on which a circuit is formed;  
a plated metal film forming unit for forming a plated metal film on said semiconductor substrate which has been carried in;  
an annealing unit for annealing said semiconductor substrate;  
a cleaning unit for cleaning said semiconductor substrate;  
a barrier layer forming unit for forming a barrier layer on said semiconductor substrate;  
and  
a transport mechanism for transporting said semiconductor substrate between said units.

68. A semiconductor substrate processing apparatus, comprising:  
a carry-in section for carrying in a semiconductor substrate having a surface on which a circuit is formed;  
a plated metal film forming unit for forming a plated metal film on said semiconductor substrate which has been carried in;  
an annealing unit for annealing said semiconductor substrate;  
a cleaning unit for cleaning said semiconductor substrate;  
a cover plating unit for forming a plated cover layer on said semiconductor substrate; and  
a transport mechanism for transporting said semiconductor substrate between said units.

69. A semiconductor substrate processing apparatus, comprising:  
a carry-in section for carrying in a semiconductor substrate having a surface on which a circuit is formed;

a plated metal film forming unit for forming a plated metal film on said semiconductor substrate which has been carried in;  
an annealing unit for annealing said semiconductor substrate;  
a cleaning unit for cleaning said semiconductor substrate; and  
a transport mechanism for transporting said semiconductor substrate between said units;  
wherein said plated metal film forming unit can perform pretreatment, plating treatment, and cleaning treatment.

70. A semiconductor substrate processing apparatus, comprising:  
an electroless plating apparatus for performing electroless plating process on a semiconductor substrate;  
an electroplating apparatus for performing electroplating process on a semiconductor substrate; and  
a cleaning and drying unit for cleaning and drying the semiconductor substrate to which plating has been applied.

71. A semiconductor substrate processing apparatus, comprising:  
a carry-in section for carrying in a semiconductor substrate having a surface on which a circuit is formed;  
a liquid supply equipment having a plating liquid tank;  
a plating module for performing plating process on a semiconductor substrate;  
a film thickness measuring unit for measuring and/or detecting a film thickness of said film and/or a surface state of said film formed on said semiconductor substrate; and  
a transport mechanism for transporting said semiconductor substrate.

72. A semiconductor substrate processing apparatus, comprising:  
a carry-in section for carrying in a semiconductor substrate having a surface on which a circuit is formed;

a liquid supply equipment having a plating liquid tank;  
a plating module for performing plating process on a semiconductor substrate;  
an annealing unit for annealing said semiconductor substrate; and  
a transport mechanism for transporting said semiconductor substrate.